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RD-26,616

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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of  
R.A. Fillion and W.E. Burdick

Applicant's Docket No. RD-26,616

For

**CHIP BURN-IN AND TEST STRUCTURE AND METHOD**

**PRELIMINARY AMENDMENT**

Honorable Commissioner of Patents and Trademarks,  
Washington, DC 20231

S I R:

Prior to examination, please amend this application as follows.

In the title, please delete "AND METHOD."

In the claims, please amend claim 12 and add claims 14-17 as follows.

<sup>1</sup>  
~~12.~~ A burn-in fixture comprising:  
burn-in frame having at least one window and including resistors having resistor pads;  
at least one integrated circuit chip having chip pads and situated in the at least one  
window;

a flexible layer attached to the burn-in frame and the at least one integrated circuit chip,  
the flexible layer having via openings extending to the chip pads and the resistor pads; and  
a pattern of electrical conductors extending over the flexible layer and extending into the  
vias [; and

means for burning in the at least one integrated circuit chip].

<sup>3</sup>  
~~14~~ (new). The fixture of claim ~~12~~<sup>1</sup> wherein the burn-in frame comprises a ceramic or  
an insulated metal.

<sup>4</sup>  
~~15~~ (new). The fixture of claim ~~14~~<sup>3</sup> wherein the flexible layer comprises a polymer.